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PATENT  
Atty. Dkt. No. AMAT/5297/DSM/LOW K/JW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Rivoire, et al.

Serial No.: 09/844,991

Confirmation No.: 1361

Filed: April 27, 2001

For: METHOD FOR PLANARIZING  
ORGANOSILICATE LAYERS

BOX NON-FEE AMENDMENT  
Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

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Group Art Unit: 3723

Examiner: Robert Rose

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APR 08 2003

TECHNOLOGY CENTER R3700

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>03/26</u> , 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.	
<u>03/26/03</u> Date	<u>Kent R. J. [Signature]</u> Signature

**RESPONSE TO RESTRICTION REQUIREMENT DATED FEBRUARY 26, 2003**

In response to the Restriction Requirement dated February 26, 2003, having a shortened statutory period for response set to expire on March 26, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5297/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**IN THE SPECIFICATION:**

Please replace paragraph [0047] with the following paragraph:

a1  
[0047] FIGS. 2a-2b illustrate schematic cross-sectional views of a substrate at different stages of an integrated circuit fabrication incorporating a planarization process. In general, the substrate 200 refers to any workpiece on which processing is performed, and the term substrate structure is used to denote the substrate 200 together with other